Shi Mao 毛适



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Education

M. Sc. @ Tsinghua University (THU)

Fall 2019 -

Data Science & Information Technology, Tsinghua-Berkeley Shenzhen Institute (TBSI)

GPA: 3.95/4.0 Rank: 2 nd /95 Excepted Graduation: 2022.06

B. E. @ South China University of Technology (SCUT)

Fall 2015 – Spring 2019

Intelligence Science & Technology, Automation Department

GPA: 3.88/4.0 Rank: 1st /51

Visiting Student @ University of California, Berkely (UCB)

Fall 2018

Computer Science & Statistics, Exchange Program Got 3A and 1B+ in all major courses

Research Experience

GigaMVS: A Benchmark for Ultra-large-scale Gigapixel-level 3D Reconstruction Sep 2020 – Oct 2021

Construct high-resolution 3D reconstruction dataset to support large scene reconstruction with fine details. Contribute to the data collection and analysis. <u>Accepted by IEEE TPAMI</u> (as co-first-auther).

Surface Material Perception Through Multimodal Learning

Aug 2021 - Apr 2022

Material perception using structured light camera by fusing reflecting, scattering and texture modalities. Contribute to the methods, theoretical analysis and experiments. Accepted by IEEE JSTSP (as first-author)

Visual system of a BCI manipulator for automatic drinking

Jun 2017– May 2018

Recognize and localize the cup for grasping by computer vision.

As a team leader of National Undergraduate Training Program. Accepted by ROBIO. (as second author)

Deciphering cortex neural signals using mesoscale imaging and electrophysiology Sep 2021 – Mar 2022

Analyze the dynamic yet distributed neural activities using imaging and electrophysiology methods.

Contribute to the neural decoding of facial expressions.

Mapping brain dynamics in unconsciousness with a human SEEG resource

Mar 2021 – Jun 2021

Characterized the neural oscillations of different consciousness state, based on SEEG implanted in human brain. Contribute to the data analysis. Under review by Brain (as co-auther).

Honors

China National Scholarship (twice)		2016 & 2017
Mathematical Contest in Modeling (MCM) Merito	rious Award	2017
8-th Mathematics competition of Chinese College Students	First Price	2016